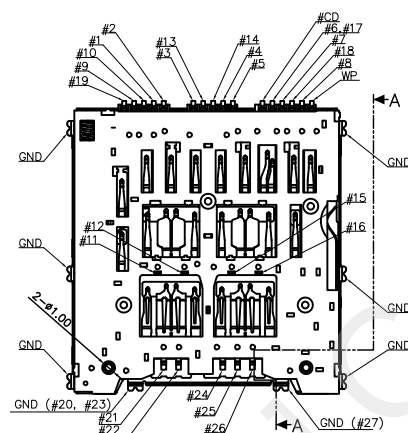
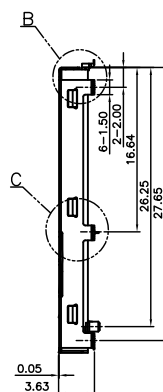
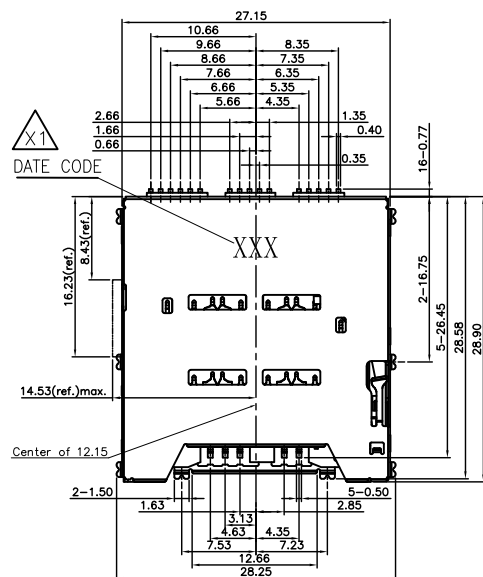
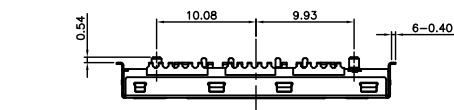




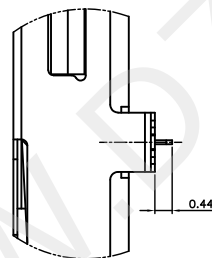
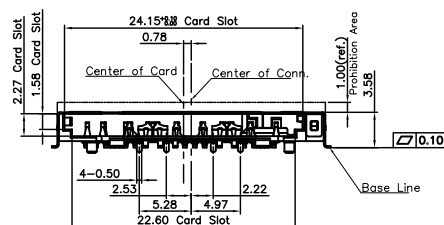
Section A-A

Date Code: 0 C Q

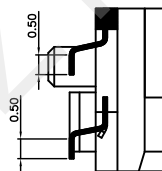

 (制程喷码依最新生产日期)

NOTE:

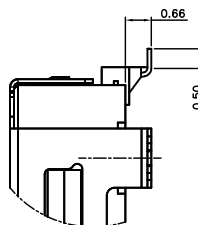
1. Material:
 - 1-1 Housing:LCP 475, Color Black UL94—V0
 - 1-2 Contact: Phosphor Bronze
 - 1-3 Cover: SUS304—H
- 2.Plating:
 - 2-1 Contact terminal:
Contact area: Gold 5u" Min.
Underplating: Ni overall 50U" Min. Solder area: Gold 5u" Min .
 - 2-2 Cover:
Underplating: Solder Ni overall 50U" Min.
3. Specification:
 - 3-1.Current Rating :0.5A max.
 - 3-2.Contact Resistance: 50 mOhms max
 - 3-3.Insulation Resistance:1000 MOhms min./500VDC
 - 3-4.Dielectric Withstanding Voltage:500 V AC/1minute
 - 3-5.Operating Temperature:—25°C to+85°C
 - 3-6.Insertion force: 9.8N Max
 - 3-7.Extraction force: 9.8N Max
 - 3-8.Durability:10000 CYCLES
4. Product Compliant to HalogenFree+ RoHS2 Directive 2002/95/EC and ELV 2000/53/EC
5. Recommending A Metal More Than 0.15mmr Thick.
Please Confirm Solderability, If Use A Metal Mask Less Than 0.15mm Thick.



Detail C
Scale 4 : 1



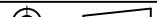
Detail D
Scale 4 : 1

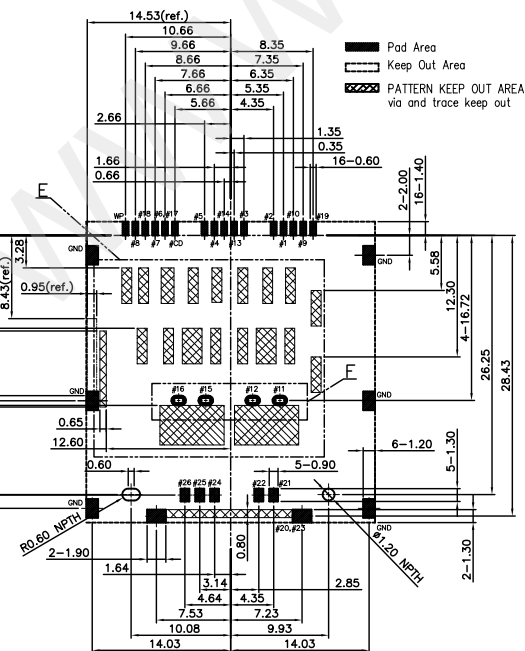
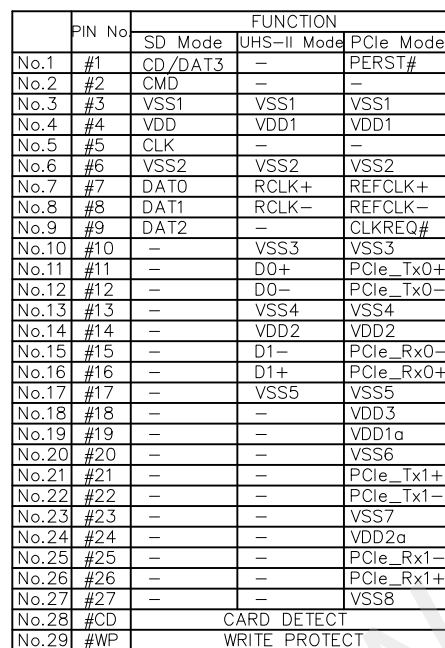


Detail B
Scale 4 : 1

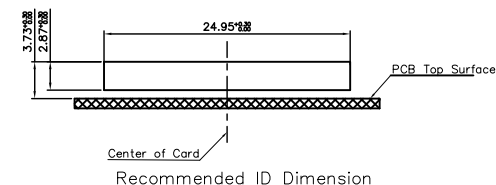


深圳市华宇创精密电子有限公司

TOLERANCE:		DRAWN BY :		DATE :		PART NAME:	
X.X ±0.30		陈一鸣		2014-02-23		SD 8.0 PUSH SMT 3.58H	
X.XX ±0.25		CHECKED BY:		DATE :		PART NO.	
X.XXX ±0.15						HYC99-SD29-358	
X: ±2° X.X ±0.5°		马跃		2014-02-23		MOLD NO.	
						APPROVED BY:	
		HYC-2509011549					
UNIT: mm [inch]		邱敏		2014-02-23		SHEET NO.	
SCALE:1:1 SIZE: A4						1 OF 1	



RECOMMEND P.C.B LAYOUT(TOP VIEW)
(Tolerances Unless Otherwise Spec. ± 0.05)



深圳市华宇创精密电子有限公司

TOLERANCE:		DRAWN BY :	DATE :	PART NAME:	
X.X ±0.30		陈一鸣	2014-02-23	SD 8.0 PUSH SMT 3.58H	
X.XX ±0.25					
X.XXX ±0.15					
X.* ±2* X.* ±0.5*		CHECKED BY:	DATE :	PART NO.	HYC99-SD29-358
		马跃	2014-02-23	MOLD NO.	
				APPROVED BY:	DATE :
UNIT: mm [inch]		邱敏	2014-02-23	SHEET NO.	1 OF 1
SCALE:1:1	SIZE: A4				